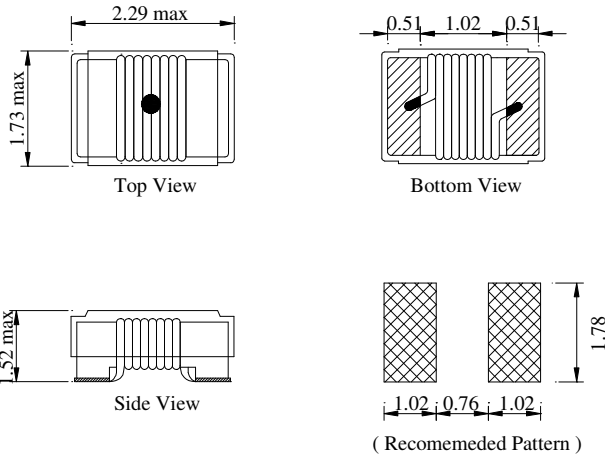


Product Specification		DOC.NO	0805CG-series
Product Description	SMD Wire Wound Ceramic Chip Inductor	Page	1
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Configuration & Dimension:



Feature:

- 1、Small and lightweight surface mounting type.
- 2、Coil body made of ceramic material in chip from High Q at high frequency.
High self-resonance frequency.
Inductance Range:2.7~2200nH.
- 3、Applicable to 100MHz~2GHz.

Application:

- 1、Bluetooth module.
- 2、Mobile communication units.
- 3、Portable telephone.
- 4、Wireless devices.

Construction & Material:

- 1、Core : Ceramic core
- 2、Wire : F Class Enameled copper wire
- 3、Terminal : Mo / Mn or W with Au
- 4、Encapsulate : UV epoxy ; Color : Transparent
- 5、Products comply with RoHS' requirements

Product Identification:

0805 C
 1 2 3 4 5

- 1、Dimension
- 2、Type: C : Standard products ., D~Z : Special products
- 3、Terminal : G : Mo / Mn or W with Gold plated.
S : Pd /Ag with Tin plated.
- 4、Inductance:
- 5、Tolerance: (G2% , J5% , K10% , M20%)

Specification / Electrical					DOC.NO	0805CG-type	
Product Description	SMD Wire Wound Ceramic Chip Inductor				Page	2	
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PART NUMBER	INDUCTANCE (n H)	Q MIN	SRF (MHz) MIN	RDC (Ω) MAX	IDC (mA) MAX	TOLERANCE	COLOR CODE
0805C 2N7	2.7@250MHz	35@1000MHz	6000	0.03	600	K, J	Brown
0805C 3N3	3.3@250MHz	50@1500MHz	7900	0.08	600	K, J	Black
0805C 5N6	5.6@250MHz	65@1000MHz	5500	0.08	600	K, J	Violet
0805C 6N8	6.8@250MHz	50@1000MHz	5500	0.11	600	K, J	Brown
0805C 7N5	7.5@250MHz	50@1000MHz	4500	0.14	600	K, J, G	Black
0805C 8N2	8.2@250MHz	50@1000MHz	4700	0.12	600	K, J, G	Red
0805C 10N	10@250MHz	60@500MHz	4200	0.10	600	K, J, G	Red
0805C 12N	12@250MHz	50@500MHz	4000	0.15	600	K, J, G	Orange
0805C 15N	15@250MHz	50@500MHz	3400	0.17	600	K, J, G	Yellow
0805C 18N	18@250MHz	50@500MHz	3300	0.20	600	K, J, G	Green
0805C 22N	22@250MHz	55@500MHz	2600	0.22	500	K, J, G	Blue
0805C 24N	24@250MHz	50@500MHz	2000	0.22	500	K, J, G	Red
0805C 27N	27@250MHz	55@500MHz	2500	0.25	500	K, J, G	Violet
0805C 33N	33@250MHz	60@500MHz	2050	0.27	500	K, J, G	Gray
0805C 36N	36@250MHz	55@500MHz	1700	0.27	500	K, J, G	Yellow
0805C 39N	39@250MHz	60@500MHz	2000	0.29	500	K, J, G	White
0805C 43N	43@200MHz	60@500MHz	1650	0.34	500	K, J, G	Yellow
0805C 47N	47@200MHz	60@500MHz	1650	0.31	500	K, J, G	Black
0805E 51N	51@200MHz	60@500MHz	1600	0.33	500	K, J, G	Violet
0805C 56N	56@200MHz	60@500MHz	1550	0.34	500	K, J, G	Brown
0805C 68N	68@200MHz	60@500MHz	1450	0.38	500	K, J, G	Red
0805C 82N	82@150MHz	65@500MHz	1300	0.42	400	K, J, G	Orange
0805C 91N	91@150MHz	65@500MHz	1200	0.48	400	K, J, G	Blue
0805C R10	100@150MHz	65@500MHz	1200	0.46	400	K, J, G	Yellow
0805C R12	120@150MHz	50@250MHz	1100	0.51	400	K, J, G	Green
0805C R15	150@100MHz	50@250MHz	920	0.56	400	K, J, G	Blue
0805C R18	180@100MHz	50@250MHz	870	0.64	400	K, J, G	Violet
0805C R22	220@100MHz	50@250MHz	850	0.70	400	K, J, G	Gray
0805C R24	240@100MHz	44@250MHz	690	1.00	350	K, J, G	Black
0805C R27	270@100MHz	48@250MHz	650	1.00	350	K, J, G	White
0805C R30	300@150MHz	25@250MHz	450	1.40	300	K, J, G	Gray
0805C R33	330@100MHz	48@250MHz	600	1.40	310	K, J, G	Black
0805C R39	390@100MHz	48@250MHz	560	1.50	290	K, J, G	Brown
0805C R47	470@50MHz	33@100MHz	375	1.76	250	K, J, G	Violet
0805C R56	560@25MHz	23@50MHz	340	1.90	230	K, J, G	Orange
0805C R68	680@25MHz	23@50MHz	188	2.20	190	K, J, G	Green
0805C R75	750@25MHz	23@50MHz	215	2.35	180	K, J, G	Blue
0805C R82	820@25MHz	23@50MHz	215	2.35	180	K, J, G	Brown
0805C 1R0	1000@25MHz	23@50MHz	260	2.70	170	K, J, G	Black
0805C 1R5	1500@25MHz	23@50MHz	170	5.00	140	K, J, G	Green
0805C 2R2	2200@25MHz	23@50MHz	170	6.00	110	K, J, G	Blue

1、 Test equipment :

L/Q : HP4287A

SRF : HP4291B,HP8753E

2、 IDC : For 15°C Temperature rise from 25°C ambient.

3、 Operating temperature : -40°C~+125°C.

CLIDER ENTERPRISE CO., Ltd.

Packaging

DOC.NO

0805CG-type

Product Description

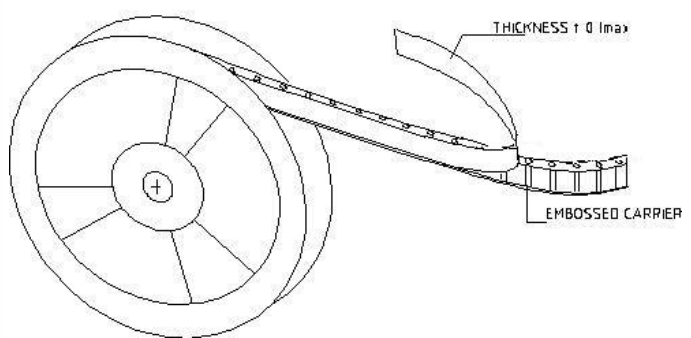
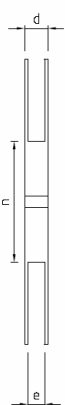
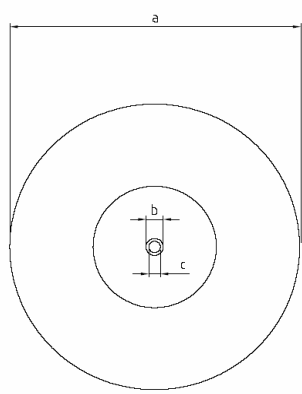
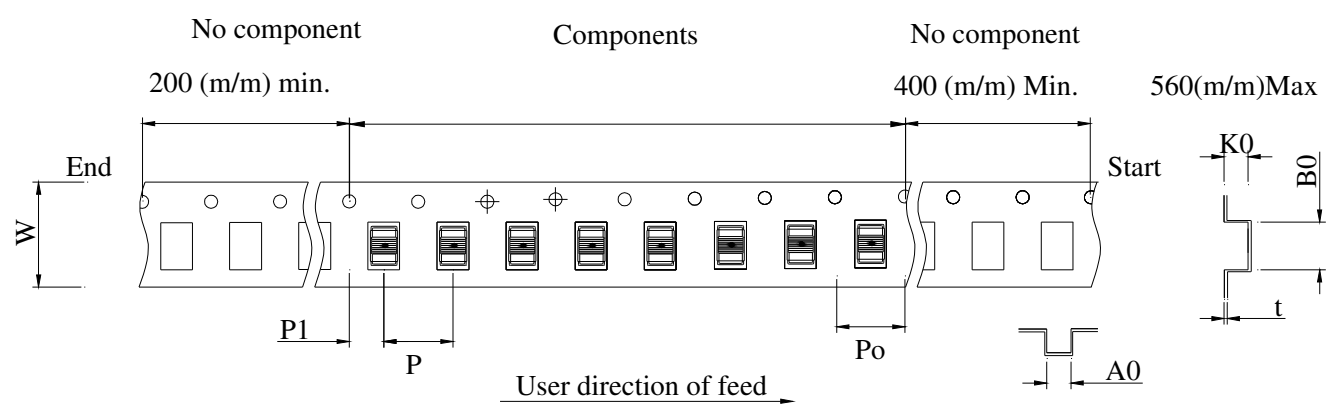
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Product Series	t	PI	P	P ₀	W	A ₀	B ₀	K ₀	a	b	c	d	e	n
0805	0.25 ±0.05	2.0 ±0.05	4.0 ±0.1	4.0 ±0.1	8.0 ±0.2	1.93 ±0.1	2.39 ±0.1	1.38 ±0.1	178.0 ±2.0	21.0 ±0.8	13.0 ±0.8	12.5 MAX	8.4 ±1.0	50 MIN

Type	Reel		5Reel / Box		6Box / Carton	
	Q'ty(Pcs)	Size m/m	Q'ty(Pcs)	Size m/m	Q'ty(Pcs)	Size m/m
B	3,000	180 φ	15,000	182×182×80	90,000	540×210×205
C	2,000	180 φ	10,000	182×182×80	60,000	540×210×205

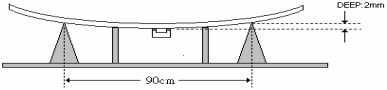
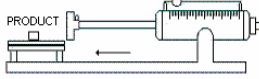
Reliability		DOC.NO	0805CG-type
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1. Environmental Performance

NO	ITEM	SPECIFICATION	TEST CONDITION	TSET METHOD		
1-1	TEMPERATURE CYCLE	APPEARANCE:NO DAMAGE L CHANGE:WITHIN±3% Q CHANGE:WITHIN±3%	ONE CYCLE		TO WRITE DOWN MEASURED RESULT FOR THE PARTS AFTER TEST AT ROOM TEMPERATURE FOR 1HOUR AND BEFRON TEST	
			STEP	TEMPERATURE(°C)		TIME(MIN)
			1	+125°C±5		30
			2	-65°C±5		30
			TOTAL:10CYCLES			
1-2	HUMIDITY RESISTANCE		TEMPERATURE:40±2°C RELATIVE HUMIDITY:90±5% TIME:96HRS	TO WRITE DOWN MEASURED RESULT FOR THE PARTS AFTER TEST AT ROOM TEMPERATURE FOR 1HOUR AND BEFRON TEST		
1-3	LIFE TEST		TEMPERATURE:+75°C±5°C TIME:300HRS	TO WRITE DOWN MEASURED RESULT FOR THE PARTS AFTER TEST AT ROOM TEMPERATURE FOR 1HOUR AND BEFRON TEST		
1-4	LOWTEMPERATURE STORAGE		TEMPERATURE:-40°C±2°C TIME:48±2HRS	TO WRITE DOWN MEASURED RESULT FOR THE PARTS AFTER TEST AT ROOM TEMPERATURE FOR 1HOUR AND BEFRON TEST		
1-5	HIGHTEMPERATURE STORAGE		TEMPERATURE:+125°C±2°C TIME: 48±2HRS	TO WRITE DOWN MEASURED RESULT FOR THE PARTS AFTER TEST AT ROOM TEMPERATURE FOR 1HOUR AND BEFRON TEST		

Reliability		DOC.NO	0805CG-type
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2. Mechanical Performance

NO	ITEM	SPECIFICATION	TEST CONDITION
2-1	VIBRATION		TEST DEVICE SHALL BE SOLDERED ON THE SUBSTRATE OSCILLATION FREQUENCY:10TO 55TO10Hz FOR 1MIN AMPLITUDE:0.75mm TIME:2HRS:FOREACH AXIS(X,Y&Z), TOTAL 6HRS
2-2	RESISTANCE TO SOLDERING HEAT		SOLDER COMPOSITION: Sn/Ag/Cu=96.5/3.0/0.5 SOLDER TEMPERATURE:260±5°C IMMERSION TIME:10±1SEC TOTAL:2 CYCLES
2-3	SOLDERABILITY	THE ELECTRODES SHALL BE AT LEAST 95% COVERED WITH NEW SOLDER COATIN	SOLDER COMPOSITION:Sn/Ag/Cu=96.5/3.0/0.5 SOLDER TEMPERATURE:230±5°C IMMERSION TIME:5±0.5SEC
2-4	FLEXURE STRENGTH	THE BEING TRIED ARTICLE CAN'T CRACK OR SHED OFF OF SITUATION.	AFTER SOLDERING A CHIP TO A TEST SUBSTRATE,BEND THE USING THE FERROMOLYBDENUM MASS TO GET DOWN THE PCB BOARD TO PRESS TO BEND THE 2 mm DEPTH AND RETURN TO AGAIN THE BREAKOUT MAINTAINING THE 10SEC. SOLDERING SHALL BE RECOMMENDED PC BOARD PATTERN AND REFLOW SOLDERING. 
2-5	TERMINAL STRENGTH	PRODUCT OF THE SERIES IS MORE THAN 4POUND	AFTER SOLDERING A CHIP TO A TEST SUBSTRATE,WITH THE 0.13~0.15mm THICK SOLDER. SOLDERING SHALL BE RECOMMENDED PC BOARD PATTERN AND REFLOW SOLDERING. THE THRUST ABOUT PUSHER PRODUCT WITH THE VELOCITY OF THE 20mms/1sec AFTER ACCOINTING TO RETURN THE NULL. 

3. Recommended Lead-Free IR Reflow Conditions :

